**IEEE P802.19**

**Wireless Coexistence**

|  |  |  |
| --- | --- | --- |
| Project | IEEE P802.19 Wireless Coexistence WG | |
| Title | **March 2017 WG Minutes** | |
| Date Submitted | March 16, 2016 | |
| Source | Steve Shellhammer Qualcomm 5775 Morehouse Drive  San Diego, CA 92121 | Voice: (858) 658-1874  E-mail: shellhammer@ieee.org |
| Re: | [] | |
| Abstract | [] | |
| Purpose | [] | |
| Notice | This document has been prepared to assist the IEEE P802.19. It is offered as a basis for discussion and is not binding on the contributing individual(s) or organization(s). The material in this document is subject to change in form and content after further study. The contributor(s) reserve(s) the right to add, amend or withdraw material contained herein. | |
| Release | The contributor acknowledges and accepts that this contribution becomes the property of IEEE and may be made publicly available by IEEE P802.19. | |

**Monday March 13, 2017**

WG chair called the meeting to order at 4:02 PM.

WG chair volunteered to be acting secretary.

Chair reviewed the agenda. The WG unanimously approved the agenda, document 802.19-17/0026r2.

Chair read the IEEE Patent Policy slides. There were no responses to the call for potentially essential patent claims.

Motion to approve the minutes from the January meeting, document 802.19-17/23r0, passed without opposition.

The chair reviewed the Opening Report, document 802.19-17/0029r0.

TG1a chair presented the TG1a opening report, document 802.19-17/0028r1.

**Motion**

Request the IEEE802 Executive Committee to approve forwarding IEEE P802.19.1a-D2.0 to Sponsor Ballot.

Move: Naotaka Sato (on behalf of TG)

Second: Chen Sun

Vote: Y: 10 / N: 0 / A: 0

Motion Passed

**Motion**

Approve PAR (document 802.19-17/0034r0) and submit to IEEE 802 executive committee

Move: Naotaka Sato

Second: Sho Furuichi

Vote: Y: 10 / N: 0 / A: 0

TG2 vice chair presented the TG2 opening report, document 802.19-17/00032r0.

Andrew Myles presented document IEEE 802.19-17/0031r1, regarding liaisons with 3GPP on LAA.

Andrew review document IEEE 802.19-17/0030r0, draft liaison to 3GPP.

The WG recessed at 5:50 PM.

**Wednesday March 15, 2017**

Chair called the meeting to order at 4:04 PM

**Motion**

Motion to confirm the PAR of P802.19.1a Amendment to IEEE Standard 802.19.1-2014 as in

<https://mentor.ieee.org/802.19/dcn/15/19-15-0028-08-0CUB-draft-cub-par.docx> and the CSD as in <https://mentor.ieee.org/802.19/dcn/15/19-15-0029-05-0CUB-draft-cub-csd.docx>

Moved: Chen Sun

Second: Jim Petronovich

Yes 7 No 0 Abstain 0

Motion Passed

Andrew review document IEEE 802.19-17/0030r3, draft liaison to 3GPP.

WG recessed at 5:01 PM

--------------------

**Thursday March 16, 2017**

Chair called the meeting to order at 4:04 PM

The TG1a Technical Editor presented the TG1a closing report, document 802.19-17/37r2.

The TG2 chair presented the TG2 closing report, document 802.19-17/39r0

Andrew reviewed draft liaison, document 802.19-17/30r7. He updated the document and accepted all changes and posted it on Mentor.

**Motion**

Approve 3GPP Liaison Document 802.19-17/30r8 and submit to the Executive Committee, and give the 802 Chair editorial license.

Move Jim Petranovich

Second Alaa Mourad

Everyone in Room

Yes 7

No 0

Abstain 0

Voting Members

Yes 5

No 0

Abstain 0

Motion Passes

WG adjourned at 4:29 PM.

**Attendance**

|  |  |
| --- | --- |
| George Calcev | Huawei R&D USA |
| William Carney | Sony Corporation |
| Ariel Feldman | Auto-Talks |
| Sho Furuichi | Sony Corporation |
| Timothy Jeffries | Huawei R&D USA |
| Igal Kotzer | General Motors Company |
| James Lansford | Qualcomm Incorporated |
| Alaa Mourad | BMW Group |
| Andrew Myles | Cisco Systems, Inc. |
| Alireza Nejatian | Ericsson AB |
| James Petranovich | ViaSat, Inc. |
| Demir Rakanovic | u-blox |
| Shigenobu Sasaki | Niigata University |
| Naotaka Sato | Sony Corporation |
| Stephen Shellhammer | Qualcomm Incorporated |
| Takenori Sumi | Mitsubishi Electric Corporation |
| Mineo Takai | Space-Time Engineering |
| Chunhui Zhu | Huawei Technologies Co. Ltd |